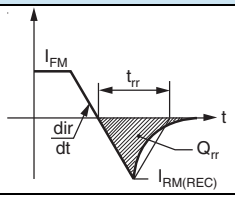
ELECTRICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum forward voltage drop	V_{FM}	10 A, T_J = 25 °C		1.2	V
Forward slope resistance	r_t	T_J = 150 °C		12.7	mΩ
Threshold voltage	$V_{F(TO)}$			1.25	V
Maximum reverse leakage current	I_{RM}	T_J = 25 °C	V_R = Rated V_{RRM}	0.1	mA
		T_J = 150 °C		2.5	

RECOVERY CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Reverse recovery time	t_{rr}	I_F at 10 A_{pk} 25 A/µs 25 °C	200	ns	
Reverse recovery current	I_{rr}		2.75	A	
Reverse recovery charge	Q_{rr}		0.32	µC	
Snap factor	S		0.6		

THERMAL - MECHANICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	T_J, T_{Stg}		-40 to +150	°C
Maximum thermal resistance junction to case	R_{thJC}	DC operation	1.5	°C/W
Maximum thermal resistance junction to ambient (PCB mount)	R_{thJA} (1)		40	
Soldering temperature	T_S		260	°C
Approximate weight			2	g
			0.07	oz.
Marking device		Case style D^2PAK (SMD-220)	10ETF02S	
			10ETF04S	
			10ETF06S	

Note

(1) When mounted on 1" square (650 mm^2) PCB of FR-4 or G-10 material 4 oz. (140 µm) copper 40 °C/W.
For recommended footprint and soldering techniques refer to application note #AN-994.

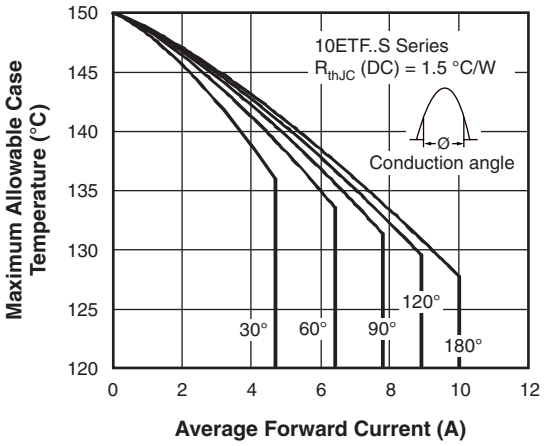


Fig. 1 - Current Rating Characteristics

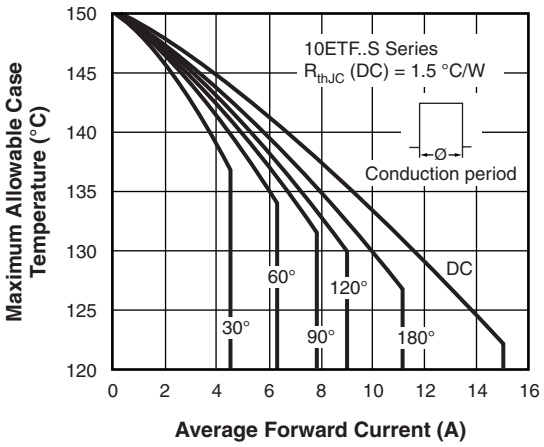


Fig. 2 - Current Rating Characteristics

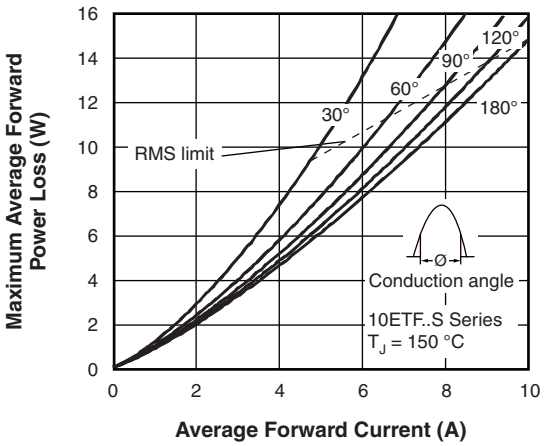


Fig. 3 - Forward Power Loss Characteristics

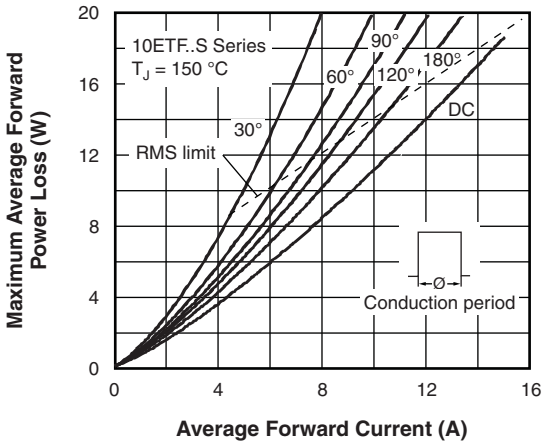


Fig. 4 - Forward Power Loss Characteristics

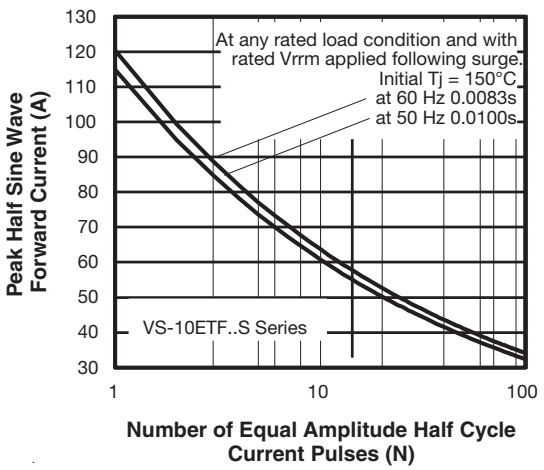


Fig. 5 - Maximum Non-Repetitive Surge Current

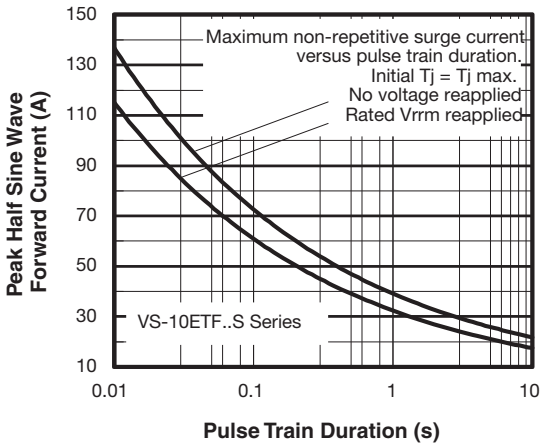


Fig. 6 - Maximum Non-Repetitive Surge Current

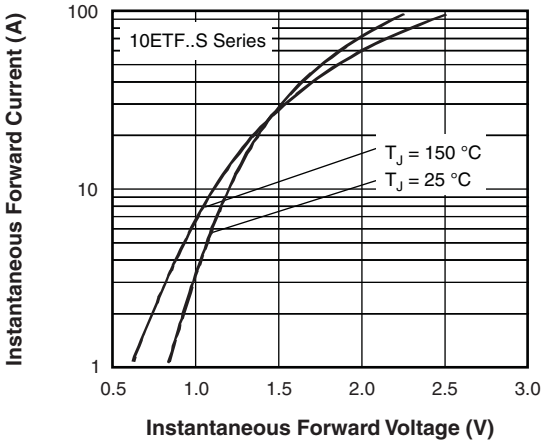


Fig. 7 - Forward Voltage Drop Characteristics

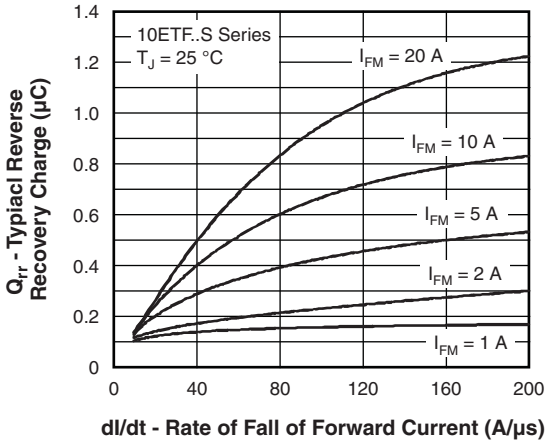


Fig. 10 - Recovery Charge Characteristics, T_J = 25 °C

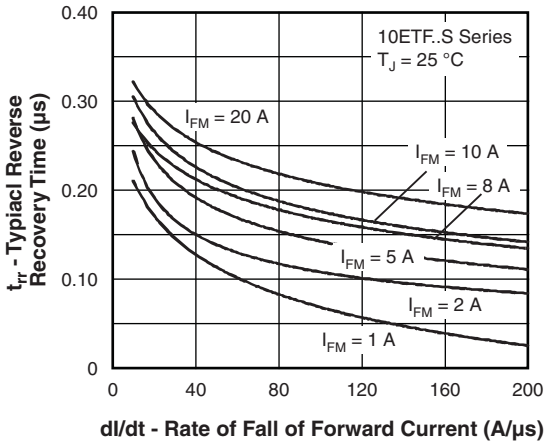


Fig. 8 - Recovery Time Characteristics, T_J = 25 °C

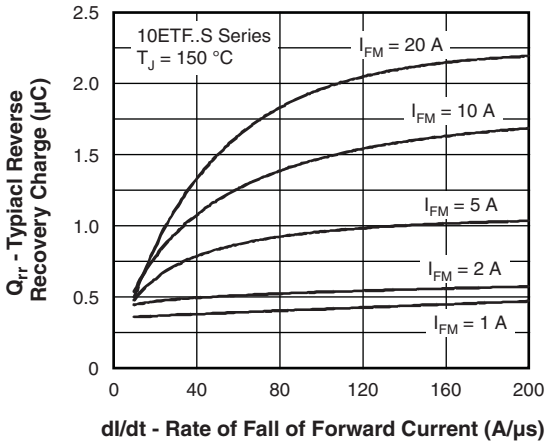


Fig. 11 - Recovery Charge Characteristics, T_J = 150 °C

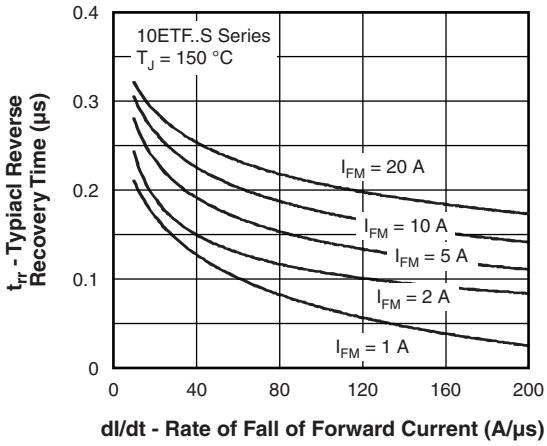


Fig. 9 - Recovery Time Characteristics, T_J = 150 °C

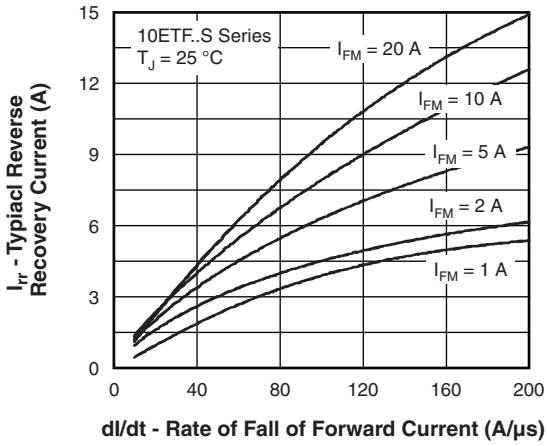


Fig. 12 - Recovery Current Characteristics, T_J = 25 °C

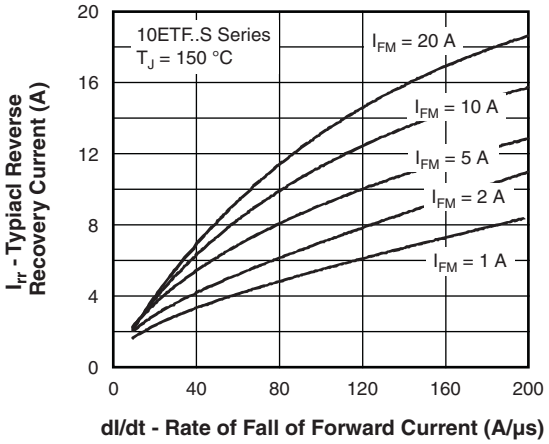


Fig. 13 - Recovery Current Characteristics, T_J = 150 °C

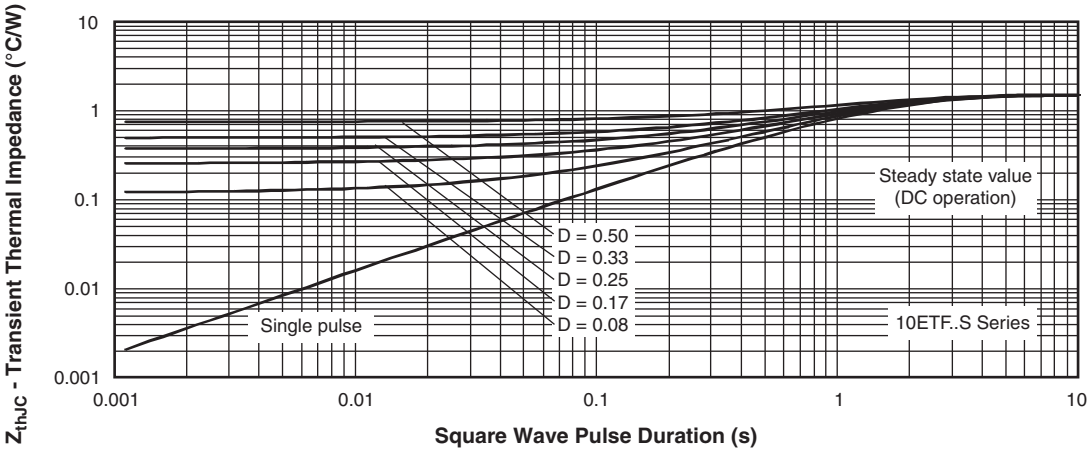


Fig. 14 - Thermal Impedance Z_{thJC} Characteristics

ORDERING INFORMATION TABLE

Device code

VS-	10	E	T	F	06	S	TRL	PbF
(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)	(9)

1 - Vishay Semiconductors product

2 - Current rating (10 = 10 A)

3 - Circuit configuration:
E = single diode

4 - Package:
T = D^2PAK (TO-220AC)

5 - Type of silicon:
F = fast soft recovery rectifier

6 - Voltage code x 100 = V_{RRM}
02 = 200 V
04 = 400 V
06 = 600 V

7 - S = surface mountable

8 - • None = tube
• TRR = tape and reel (right oriented)
• TRL = tape and reel (left oriented)

9 - PbF = lead (Pb)-free

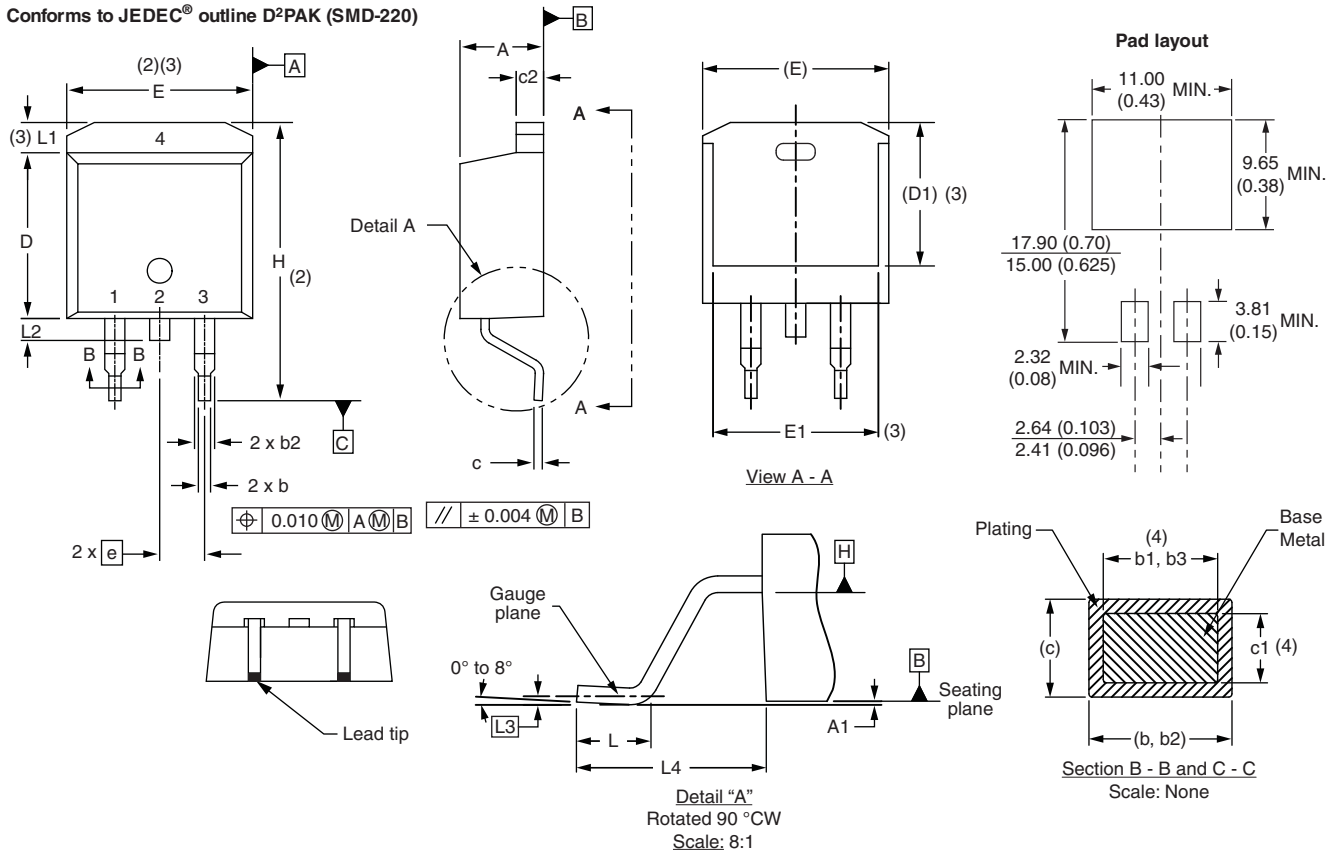
ORDERING INFORMATION (Example)

PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-10ETF02SPbF	50	1000	Antistatic plastic tubes
VS-10ETF02STRRPbF	800	800	13" diameter reel
VS-10ETF02STRLPbF	800	800	13" diameter reel
VS-10ETF04SPbF	50	1000	Antistatic plastic tubes
VS-10ETF04STRRPbF	800	800	13" diameter reel
VS-10ETF04STRLPbF	800	800	13" diameter reel
VS-10ETF06SPbF	50	1000	Antistatic plastic tubes
VS-10ETF06STRRPbF	800	800	13" diameter reel
VS-10ETF06STRLPbF	800	800	13" diameter reel

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95046
Part marking information	www.vishay.com/doc?95054
Packaging information	www.vishay.com/doc?95032

D²PAK

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190		D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010		E	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039		E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4	e	2.54 BSC		0.100 BSC		
b2	1.14	1.78	0.045	0.070		H	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4	L	1.78	2.79	0.070	0.110	
c	0.38	0.74	0.015	0.029		L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4	L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065		L3	0.25 BSC		0.010 BSC		
D	8.51	9.65	0.335	0.380	2	L4	4.78	5.28	0.188	0.208	

Notes

(1) Dimensioning and tolerancing per ASME Y14.5 M-1994

(2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body

(3) Thermal pad contour optional within dimension E, L1, D1 and E1

(4) Dimension b1 and c1 apply to base metal only

(5) Datum A and B to be determined at datum plane H

(6) Controlling dimension: inch

(7) Outline conforms to JEDEC® outline TO-263AB

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